

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	44	(micro adj3 probe) same test\$4 same ((integrated near2 circuit) or IC or chip or chips or device or devices)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/18 11:04
2	BRS	L2	19851	deposit\$4 near4 oxide near8 (substrate or substrates or wafer or wafers)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/18 11:05
3	BRS	L3	386	2 same lithograph\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/18 11:05
4	BRS	L4	43751	(sputter\$4 or CVD) near4 (metal or aluminum or electrode or conductive)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/18 11:07
5	BRS	L5	105	3 and 4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/18 11:08

	Type	L #	Hits	Search Text	DBs	Tim Stamp
6	BRS	L6	13	5 and probe	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/18 11:09

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L3	1476	lithograph\$4 same (deposit\$4 near\$4 oxide)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/18 13:54
2	BRS	L4	181	3 same sputter\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/18 14:07
3	BRS	L5	10	4 and probe	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/18 14:08
4	BRS	L6	34	<i>L1</i> (micro adj2 tip) ^{as} same (microprobe or (micro adj2 probe))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/18 14:19
5	BRS	L7	792	micro adj3 tip	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/18 14:37

*L2 (second! or addition\$4 or another) near\$4
 (sputter\$4) [new\$4 (metal or Al or aluminum ...)]*

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L8	775	micro adj3 probe	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/08/18 14:38

L1 same L2